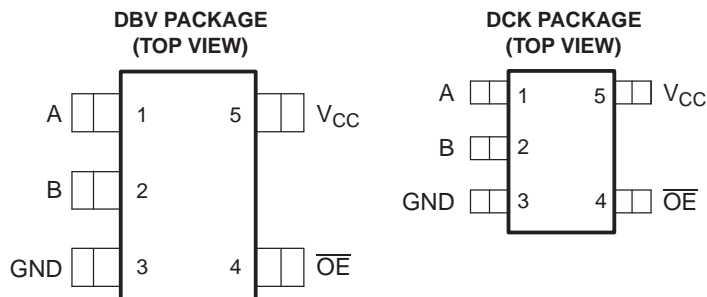


## FEATURES

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Control Input Levels



See mechanical drawings for dimensions.

## DESCRIPTION/ORDERING INFORMATION

The SN74CBT1G384 features a single high-speed line switch. The switch is disabled when the output-enable ( $\overline{OE}$ ) input is high.

### ORDERING INFORMATION

$T_A$	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(2)</sup>
-40°C to 85°C	SOT (SOT-23) – DBV	Reel of 3000	SN74CBT1G384DBVR	S8D_
		Reel of 250	SN74CBT1G384DBVT	
	SOT (SC-70) – DCK	Reel of 3000	SN74CBT1G384DCKR	S8_
		Reel of 250	SN74CBT1G384DCKT	

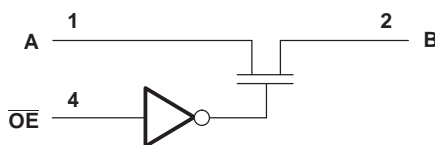
(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

(2) The actual top-side marking has one additional character that designates the assembly/test site.

### FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

### LOGIC DIAGRAM (POSITIVE LOGIC)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

# SN74CBT1G384

## SINGLE FET BUS SWITCH

SCDS065G–JULY 1998–REVISED JUNE 2006

### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	7	V
$V_I$	Input voltage range <sup>(2)</sup>	-0.5	7	V
	Continuous channel current		128	mA
$I_{IK}$	Input clamp current	$V_{I/O} < 0$	-50	mA
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>	DBV package	206	°C/W
		DCK package	252	
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

### Recommended Operating Conditions<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	4	5.5	V
$V_{IH}$	High-level control input voltage	2		V
$V_{IL}$	Low-level control input voltage		0.8	V
$T_A$	Operating free-air temperature	-40	85	°C

- (1) All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ , $I_I = -18\text{ mA}$			-1.2	V
$I_I$	$V_{CC} = 5.5\text{ V}$ , $V_I = 5.5\text{ V}$ or GND			±1	μA
$I_{CC}$	$V_{CC} = 5.5\text{ V}$ , $I_O = 0$ , $V_I = V_{CC}$ or GND			1	μA
$C_i$	Control input $V_I = 3\text{ V}$ or 0			3	pF
$C_{i(OFF)}$	$V_O = 3\text{ V}$ or 0, $\overline{OE} = V_{CC}$			4	pF
$r_{on}$ <sup>(2)</sup>	$V_{CC} = 4\text{ V}$ , TYP at $V_{CC} = 4\text{ V}$ , $V_I = 2.4\text{ V}$ , $I_I = 15\text{ mA}$			14	20
	$V_{CC} = 4.5\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$	5	7
			$I_I = 30\text{ mA}$	5	7
		$V_I = 2.4\text{ V}$ , $I_I = 15\text{ mA}$			10

- (1) All typical values are at  $V_{CC} = 5\text{ V}$  (unless otherwise noted),  $T_A = 25^\circ\text{C}$ .
- (2) Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower voltage of the two (A or B) terminals.

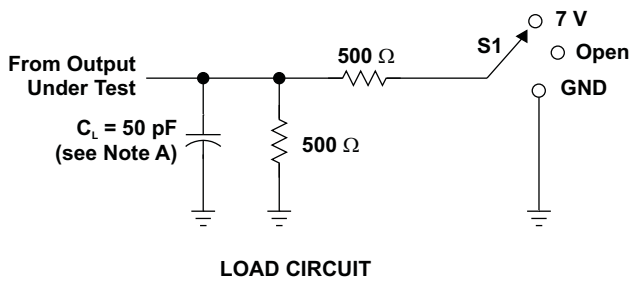
## Switching Characteristics

over recommended operating free-air temperature range,  $C_L = 50$  pF (unless otherwise noted) (see [Figure 1](#))

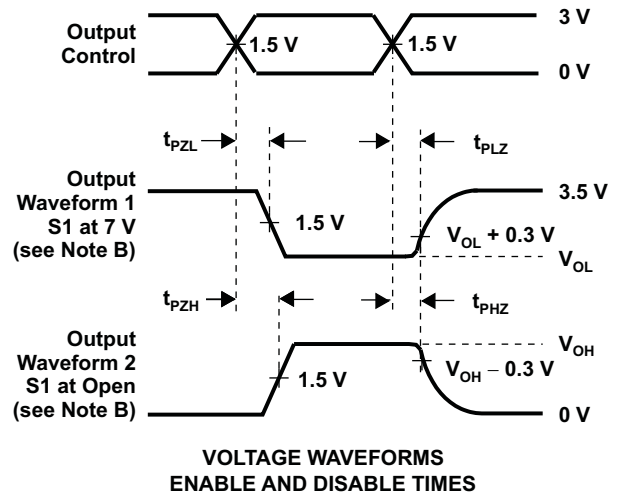
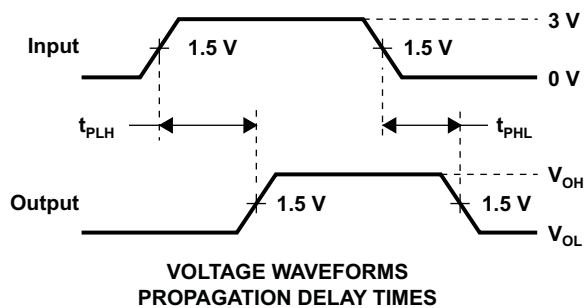
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V $\pm 0.5$ V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{(1)}$	A or B	B or A		0.35		0.25	ns
$t_{en}$	$\overline{OE}$	A or B		5.5	1.6	4.9	ns
$t_{dis}$	$\overline{OE}$	A or B		4.5	1	4.2	ns

- (1) The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

**PARAMETER MEASUREMENT INFORMATION**



TEST	S1
$t_{pd}$	Open
$t_{pLZ}/t_{pZL}$	7 V
$t_{pHZ}/t_{pZH}$	Open



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
  - D. The output is measured with one input transition per measurement.
  - E.  $t_{pLZ}$  and  $t_{pHZ}$  are the same as  $t_{dis}$ .
  - H.  $t_{pZL}$  and  $t_{pZH}$  are the same as  $t_{en}$ .
  - G.  $t_{pLH}$  and  $t_{pHL}$  are the same as  $t_{pd}$ .

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74CBT1G384DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(S8DG ~ S8DJ ~ S8DR)	<a href="#">Samples</a>
SN74CBT1G384DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(S8DG ~ S8DJ ~ S8DR)	<a href="#">Samples</a>
SN74CBT1G384DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	S8DR	<a href="#">Samples</a>
SN74CBT1G384DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(S83 ~ S8G ~ S8R ~ S8U)	<a href="#">Samples</a>
SN74CBT1G384DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(S83 ~ S8R)	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

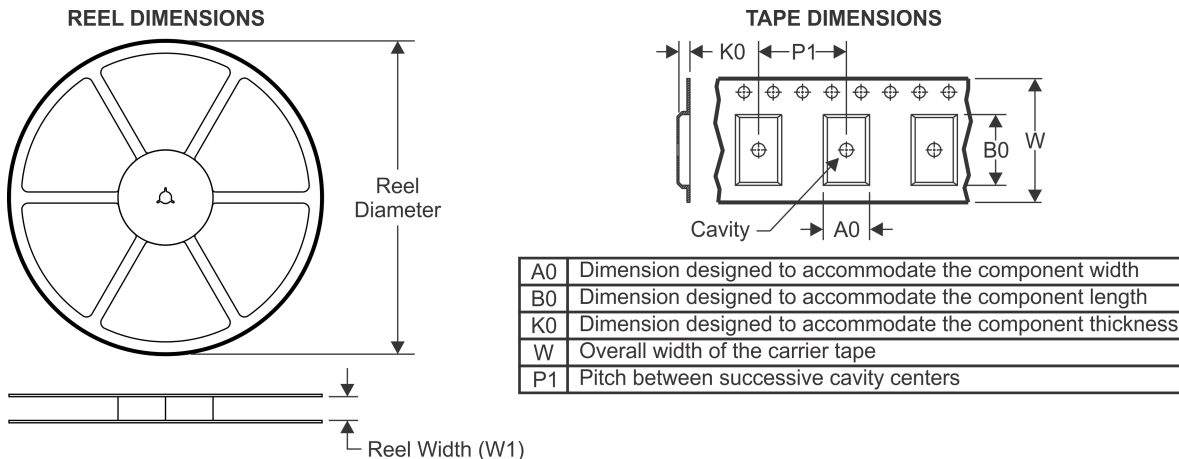
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT1G384DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74CBT1G384DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74CBT1G384DBVT	SOT-23	DBV	5	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74CBT1G384DCKR	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
SN74CBT1G384DCKT	SC70	DCK	5	250	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3

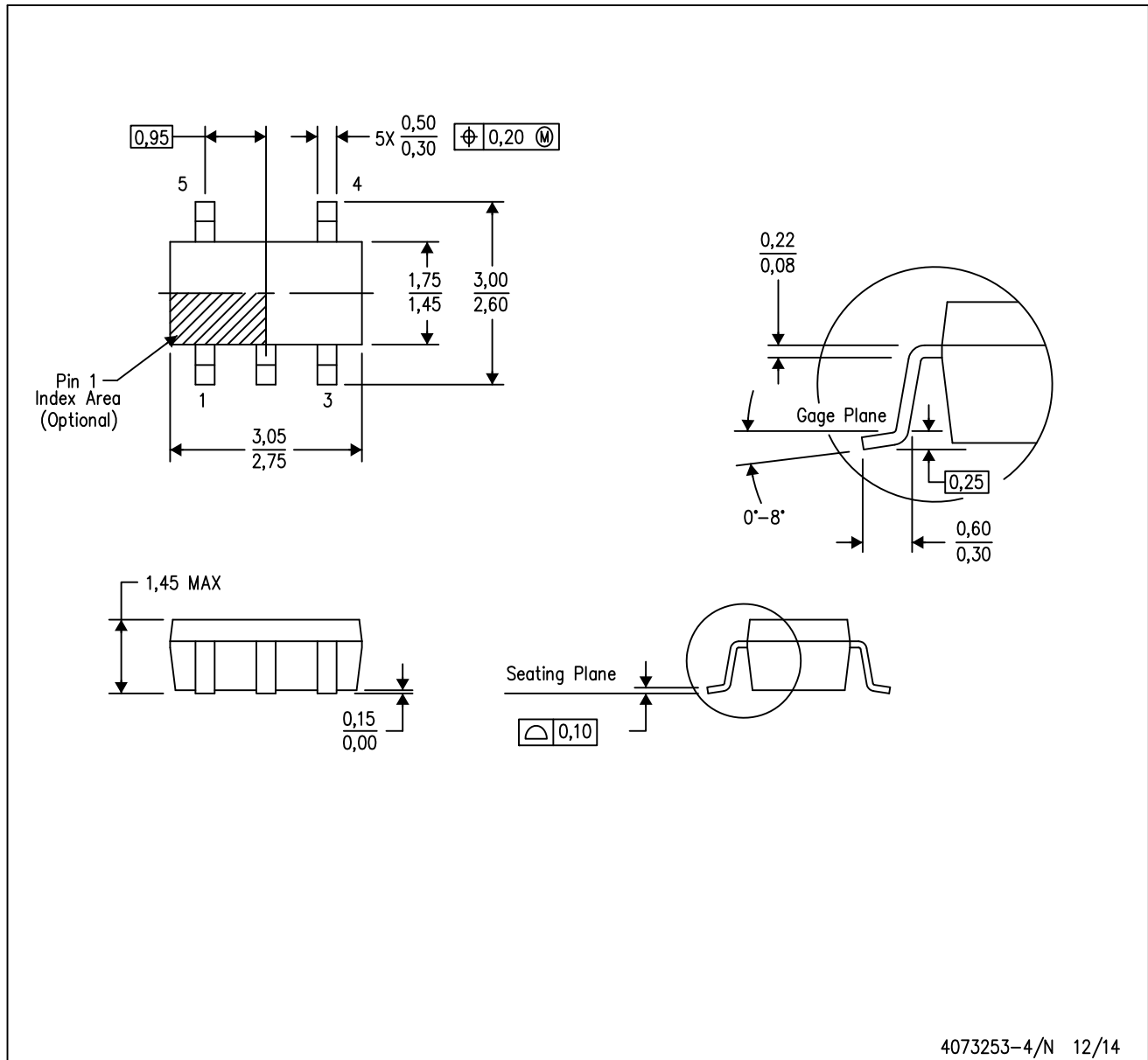
**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT1G384DBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
SN74CBT1G384DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74CBT1G384DBVT	SOT-23	DBV	5	250	202.0	201.0	28.0
SN74CBT1G384DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
SN74CBT1G384DCKT	SC70	DCK	5	250	202.0	201.0	28.0

DBV (R-PDSO-G5)

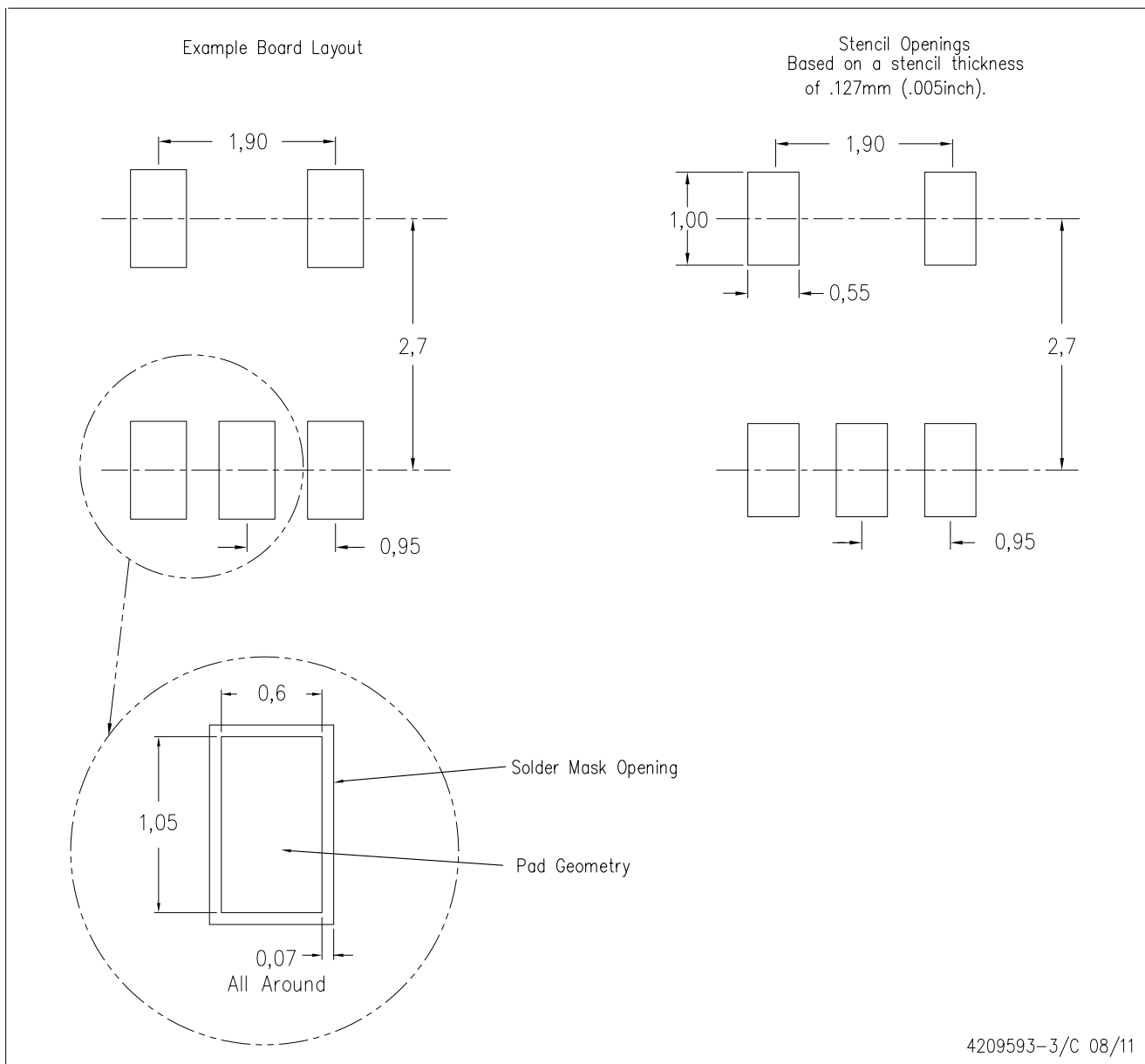
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

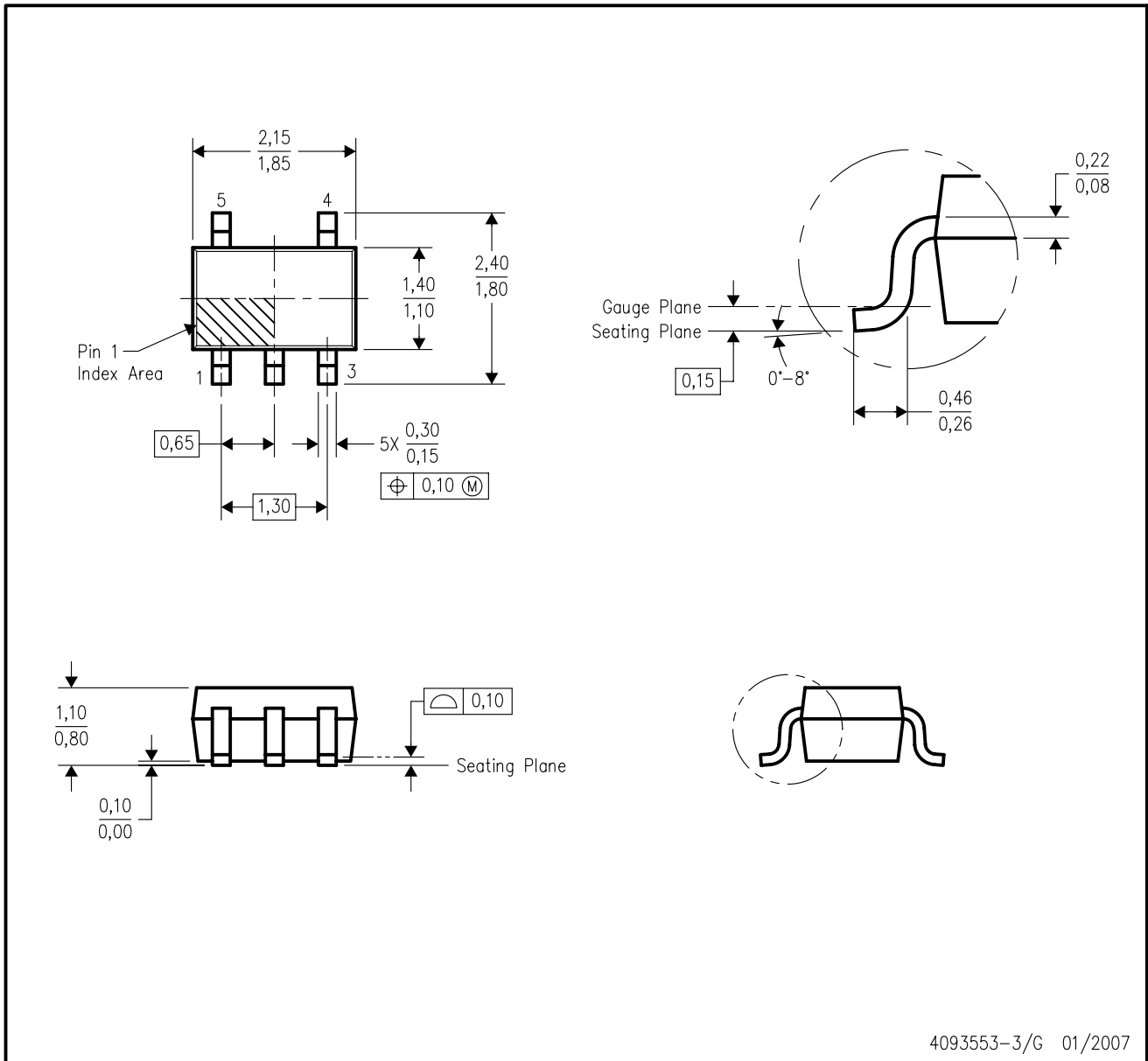
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DCK (R-PDSO-G5)

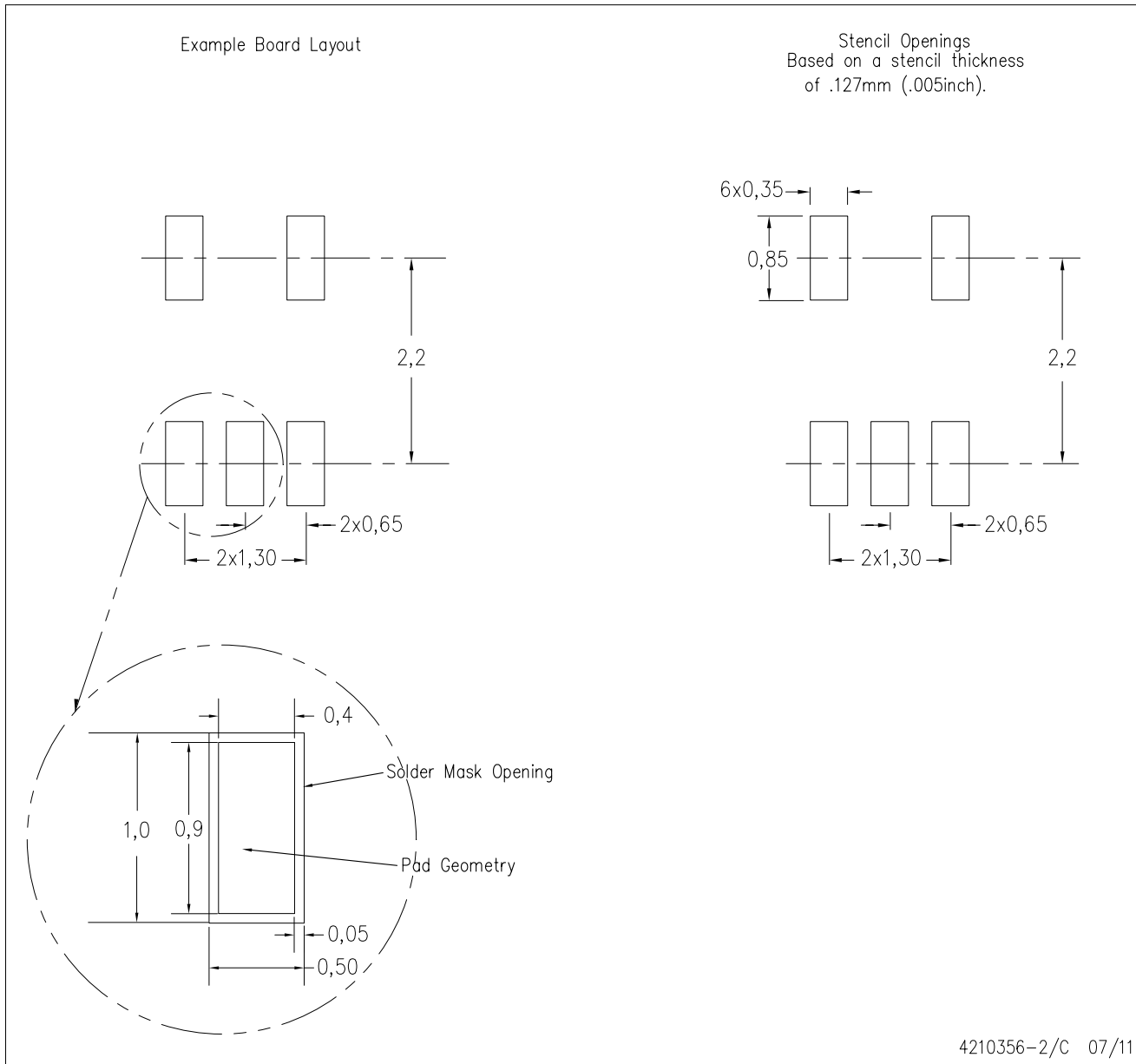
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-203 variation AA.

DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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